# **S2ABF THRU S2MBF**

## SURFACE MOUNT GENERAL PURPOSE SILICON RECTIFIER

Reverse Voltage – 50 to 1000 V

Forward Current – 2 A

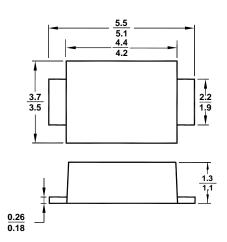
### **Features**

- Glass Passivated Chip Juntion
- · For surface mount applications
- · Low profile package
- · Easy pick and place

#### **Mechanical Data**

· Case: SMBF

 Terminals: Solderable per MIL-STD-750, method 2026



**SMBF** 

All Dimensions in mm

## **Maximum Ratings and Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	S2ABF	S2BBF	S2DBF	S2GBF	S2JBF	S2KBF	S2MBF	Units
	Marking	S2AB	S2BB	S2DB	S2GB	S2JB	S2KB	S2MB	-
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T <sub>a</sub> = 65°C	I <sub>F(AV)</sub>	2						А	
Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	60						А	
Maximum Forward Voltage at 2 A	V <sub>F</sub>	1.1						V	
Maximum DC Reverse Current $T_a = 25^{\circ}$ C at Rated DC Blocking Voltage $T_a = 125^{\circ}$ C	I <sub>R</sub>	5 100							μA
Typical Junction Capacitance at $V_R = 4 V$ , $f = 1 MHz$	С	30						pF	
Typical Thermal Resistance 1)	$R_{\theta JA}$	55							°C/W
Operating and Storage Temperature Range	$T_j$ , $T_{stg}$	- 55 to + 150						°C	

 $<sup>^{1)}</sup>$  P.C.B. mounted with 0.5 X 0.5" ( 12.7 X 12.7 mm) copper pad areas.

Fig.1 Forward Current Derating Curve

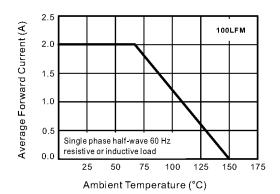


Fig.2 Typical Reverse Characteristics

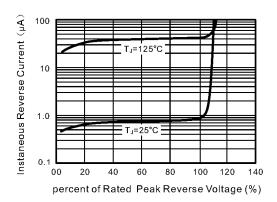
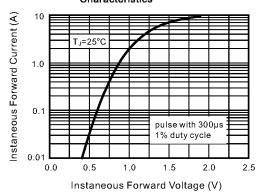


Fig.3 Typical Instaneous Forward Characteristics



100 T<sub>J</sub>=25°C T<sub></sub>

Fig.6 Maximum Non-Repetitive Peak Forward Surage Current

